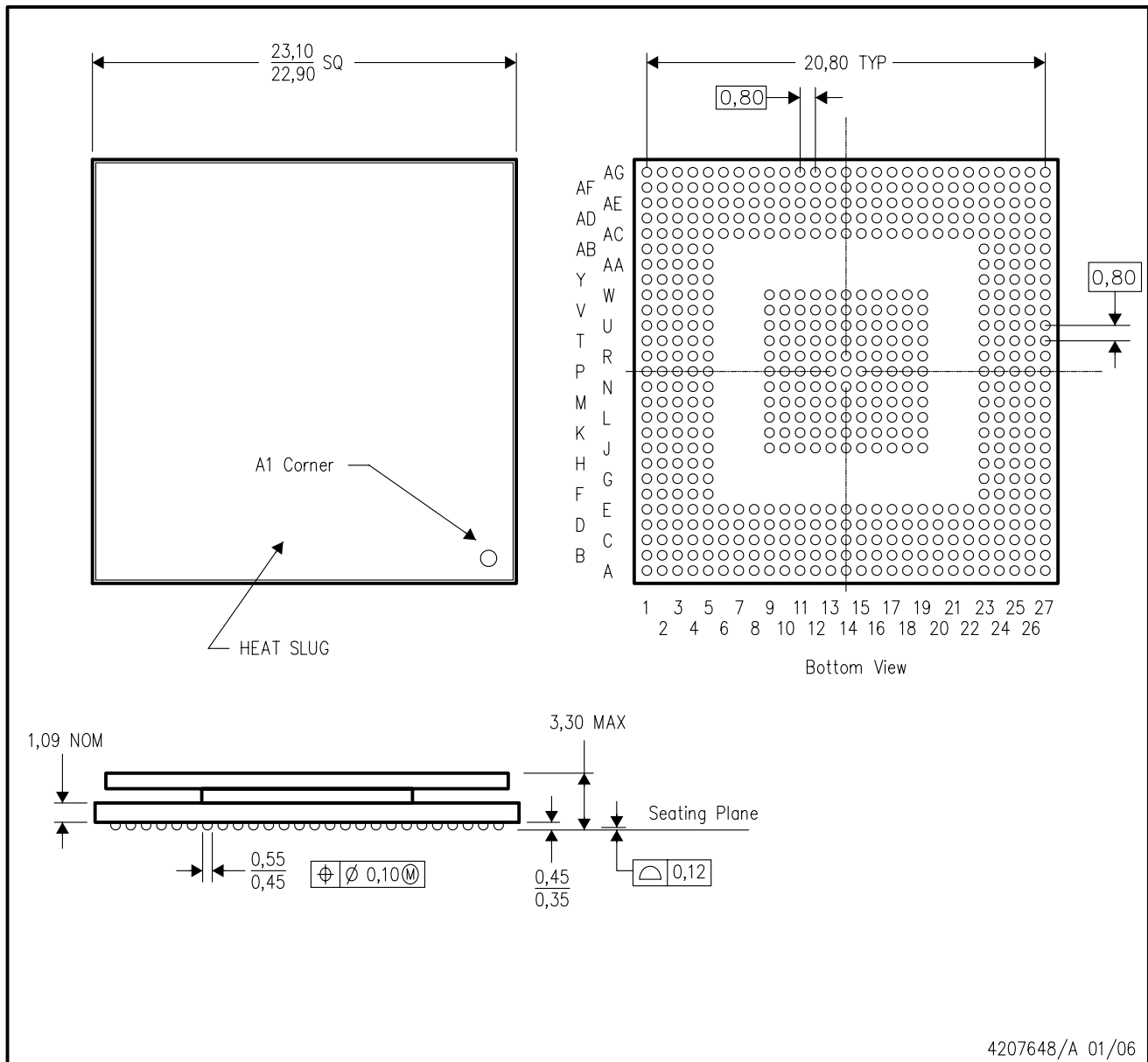


ZUN (S-PBGA-N561)

PLASTIC BALL GRID ARRAY



4207648/A 01/06

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Thermally enhanced plastic package with heat slug (HSL).
 - D. Flip chip application only.
 - E. This package is lead-free.

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